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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10008700	FILING DATE 12/07/2001	CLASS 438	SUBCLASS 764	GAU 2812	EXAMINER L44
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2825

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 2000-74315 12/07/2000

PG-PUB DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO 5648-905
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials	
TITLE: Methods of manufacturing integrated circuit devices having an encapsulated insulation layer	

U.S. DEPT. OF COMM./PAT. & TM-PTO-436 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
Assistant Examiner		Total Claims	Print Claim for O.G.
		DRAWING	
ISSUE FEE		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Application Examiner	
PREPARED FOR ISSUE		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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